

# FGB20N60SFD

## 600V, 20A Field Stop IGBT

### Features

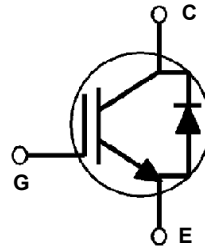
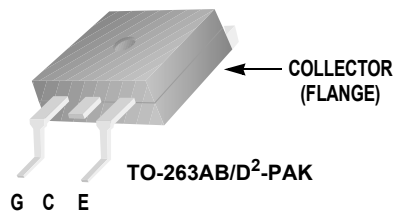
- High Current Capability
- Low Saturation Voltage:  $V_{CE(sat)} = 2.2V @ I_C = 20A$
- High Input Impedance
- Fast Switching
- RoHS Compliant

### Applications

- Welder, UPS, SMPS, PFC

### General Description

Using Novel Field Stop IGBT Technology, Fairchild's new series of Field Stop IGBTs offer the optimum performance for Welder, UPS, SMPS and PFC applications where low conduction and switching losses are essential.



### Absolute Maximum Ratings

Symbol	Description	Ratings	Units
$V_{CES}$	Collector to Emitter Voltage	600	V
$V_{GES}$	Gate to Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_C = 25^\circ C$	40	A
	Collector Current @ $T_C = 100^\circ C$	20	A
$I_{CM(1)}$	Pulsed Collector Current @ $T_C = 25^\circ C$	60	A
$I_F$	Diode Forward Current @ $T_C = 25^\circ C$	20	A
	Diode Forward Current @ $T_C = 100^\circ C$	10	A
$I_{FM(1)}$	Pulsed Diode Maximum Forward Current	60	A
$P_D$	Maximum Power Dissipation @ $T_C = 25^\circ C$	208	W
	Maximum Power Dissipation @ $T_C = 100^\circ C$	83	W
$T_J$	Operating Junction Temperature	-55 to +150	$^\circ C$
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ C$
$T_L$	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ C$

**Notes:**

1: Repetitive rating: Pulse width limited by max. junction temperature

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.6	$^{\circ}C/W$
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	2.6	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (PCB Mount)(2)	-	40	$^{\circ}C/W$

**Notes:**

2: Mounted on 1" square PCB (FR4 or G-10 material)

## Package Marking and Ordering Information

Device Marking	Device	Package	Rel Size	Tape Width	Quantity
FGB20N60SFD	FGB20N60SFD	TO-263AB/D2-PAK	13" Dia	-	800

## Electrical Characteristics of the IGBT $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$BV_{CES}$	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 250\mu A$	600	-	-	V
$\frac{\Delta BV_{CES}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_C = 250\mu A$	-	0.6	-	$V/^{\circ}C$
$I_{CES}$	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	250	$\mu A$
$I_{GES}$	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	$\pm 400$	nA
<b>On Characteristics</b>						
$V_{GE(th)}$	G-E Threshold Voltage	$I_C = 250\mu A, V_{CE} = V_{GE}$	4.0	5.0	6.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C = 20A, V_{GE} = 15V$	-	2.2	2.8	V
		$I_C = 20A, V_{GE} = 15V, T_C = 125^{\circ}C$	-	2.4	-	V
<b>Dynamic Characteristics</b>						
$C_{ies}$	Input Capacitance	$V_{CE} = 30V, V_{GE} = 0V, f = 1MHz$	-	940	-	pF
$C_{oes}$	Output Capacitance		-	110	-	pF
$C_{res}$	Reverse Transfer Capacitance		-	40	-	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 400V, I_C = 20A, R_G = 10\Omega, V_{GE} = 15V, \text{Inductive Load}, T_C = 25^{\circ}C$	-	13	-	ns
$t_r$	Rise Time		-	16	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	90	-	ns
$t_f$	Fall Time		-	24	48	ns
$E_{on}$	Turn-On Switching Loss		-	0.37	-	mJ
$E_{off}$	Turn-Off Switching Loss		-	0.16	-	mJ
$E_{ts}$	Total Switching Loss		-	0.53	-	mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 400V, I_C = 20A, R_G = 10\Omega, V_{GE} = 15V, \text{Inductive Load}, T_C = 125^{\circ}C$	-	12	-	ns
$t_r$	Rise Time		-	16	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	95	-	ns
$t_f$	Fall Time		-	28	-	ns
$E_{on}$	Turn-On Switching Loss		-	0.4	-	mJ
$E_{off}$	Turn-Off Switching Loss		-	0.28	-	mJ
$E_{ts}$	Total Switching Loss		-	0.69	-	mJ

**Electrical Characteristics of the IGBT**  $T_C = 25^\circ\text{C}$  unless otherwise noted

$Q_g$	Total Gate Charge	$V_{CE} = 400\text{V}, I_C = 20\text{A},$ $V_{GE} = 15\text{V}$	-	65	-	nC
$Q_{ge}$	Gate to Emitter Charge		-	7	-	nC
$Q_{gc}$	Gate to Collector Charge		-	33	-	nC

**Electrical Characteristics of the Diode**  $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Typ.	Max	Units
$V_{FM}$	Diode Forward Voltage	$I_F = 10\text{A}$	$T_C = 25^\circ\text{C}$	-	1.9	2.5	V
			$T_C = 125^\circ\text{C}$	-	1.7	-	
$t_{rr}$	Diode Reverse Recovery Time	$I_F = 10\text{A}, dI_F/dt = 200\text{A}/\mu\text{s}$	$T_C = 25^\circ\text{C}$	-	34	-	ns
			$T_C = 125^\circ\text{C}$	-	57	-	
$Q_{rr}$	Diode Reverse Recovery Charge		$T_C = 25^\circ\text{C}$	-	41	-	nC
			$T_C = 125^\circ\text{C}$	-	96	-	

## Typical Performance Characteristics

Figure 1. Typical Output Characteristics

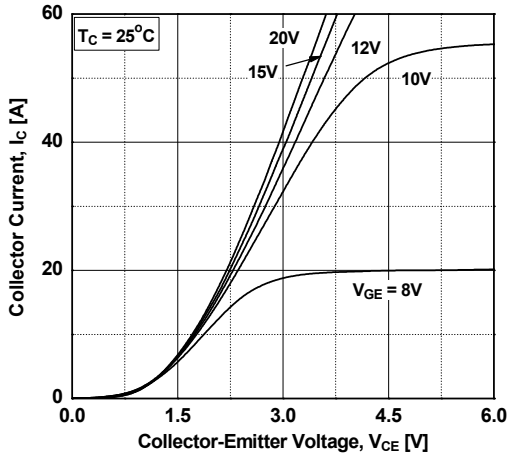


Figure 2. Typical Output Characteristics

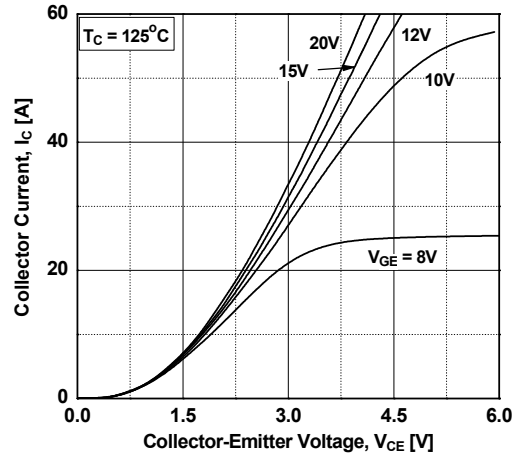


Figure 3. Typical Saturation Voltage Characteristics

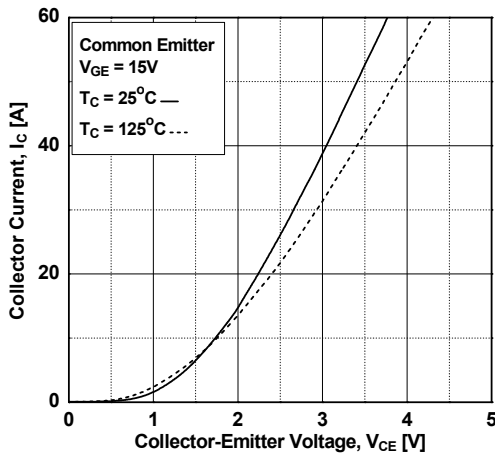


Figure 4. Transfer Characteristics

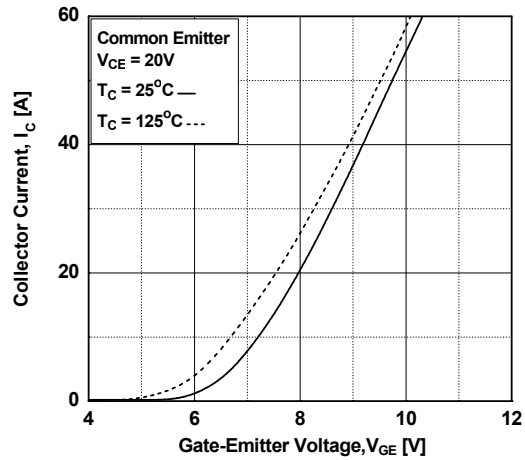


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

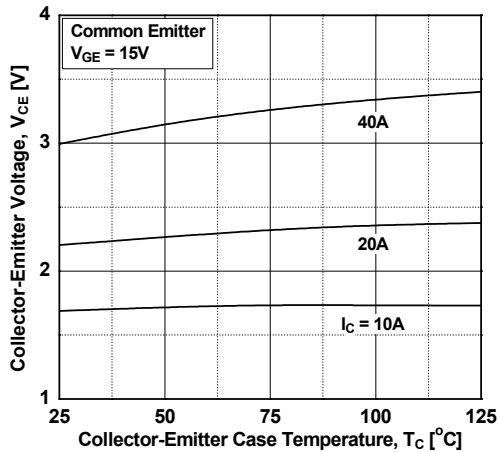
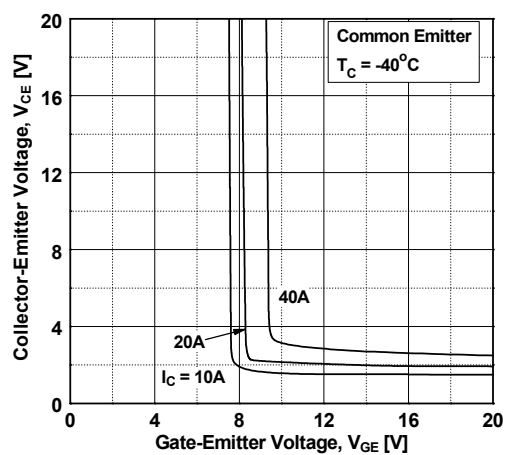


Figure 6. Saturation Voltage vs. Vge



## Typical Performance Characteristics

Figure 7. Saturation Voltage vs.  $V_{GE}$

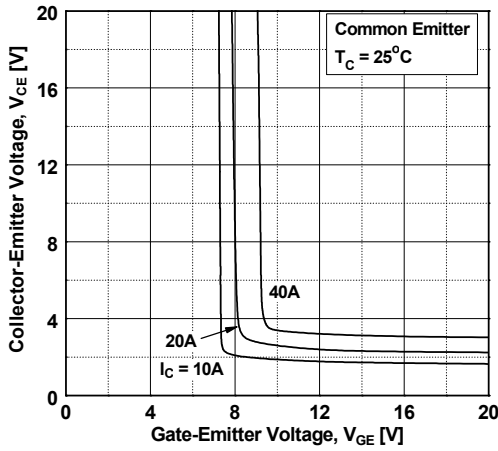


Figure 8. Saturation Voltage vs.  $V_{GE}$

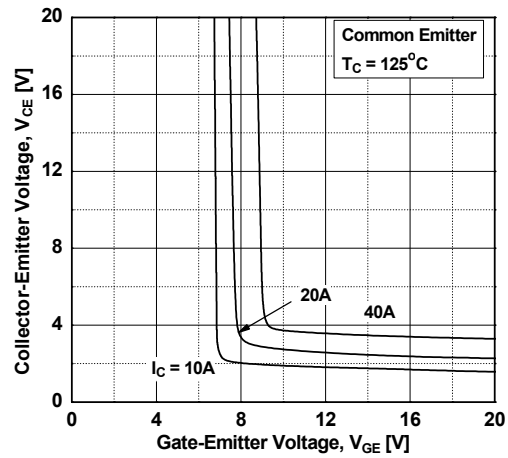


Figure 9. Capacitance Characteristics

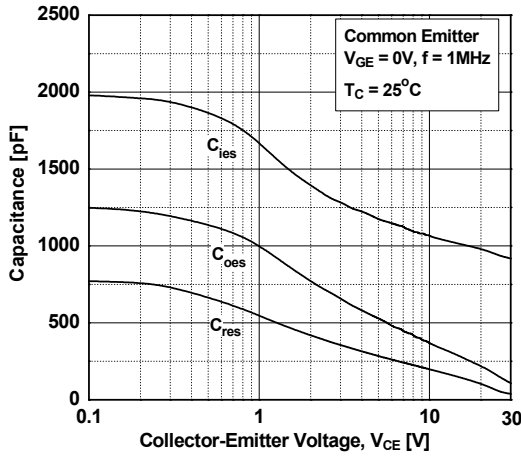


Figure 10. Gate charge Characteristics

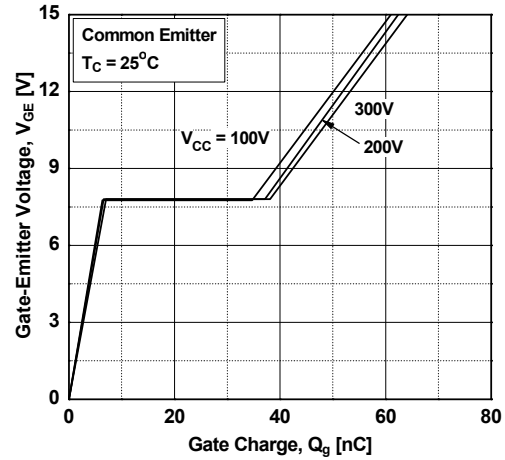


Figure 11. SOA Characteristics

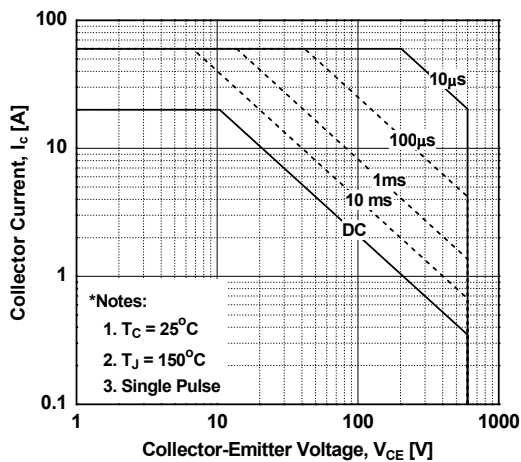
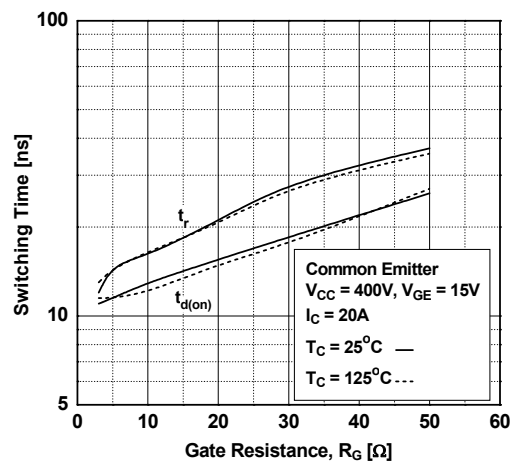
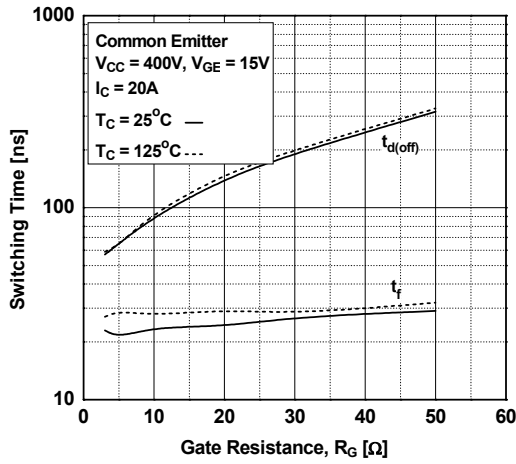


Figure 12. Turn-on Characteristics vs. Gate Resistance

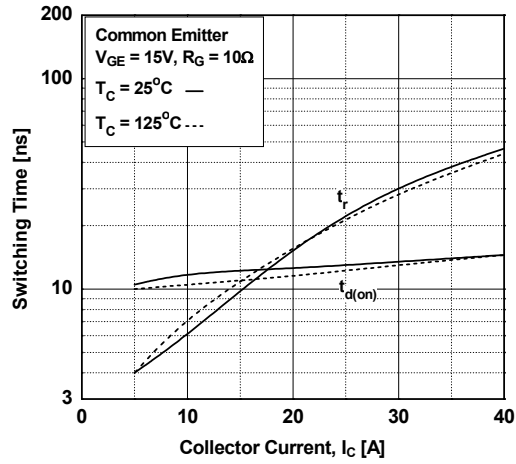


## Typical Performance Characteristics

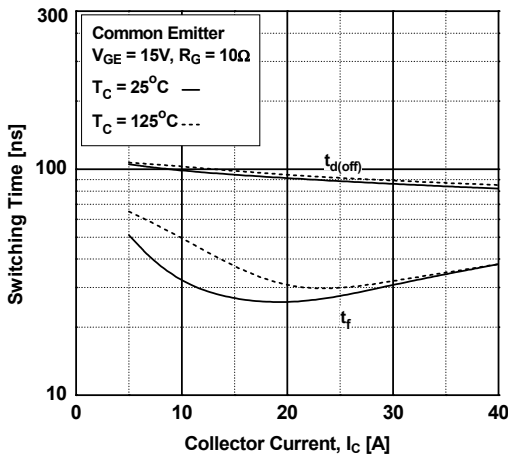
**Figure 13. Turn-off Characteristics vs. Gate Resistance**



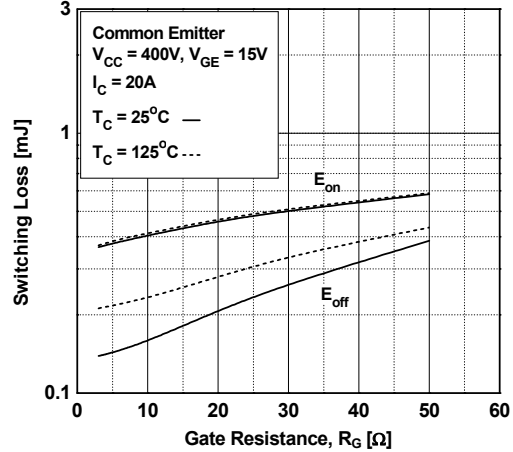
**Figure 14. Turn-on Characteristics vs. Collector Current**



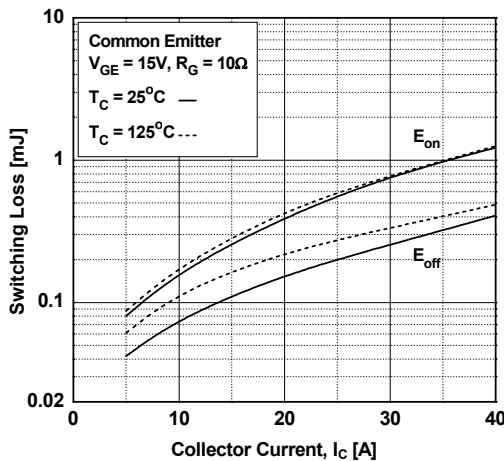
**Figure 15. Turn-off Characteristics vs. Collector Current**



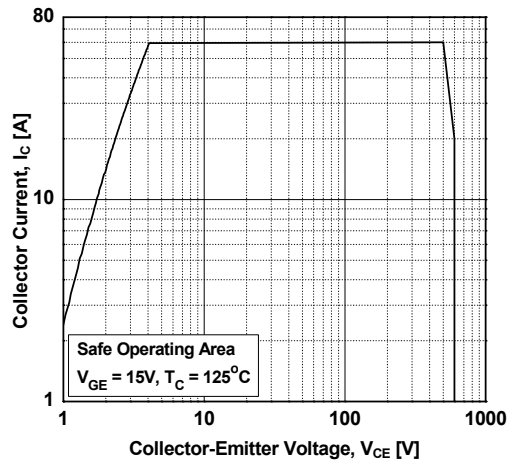
**Figure 16. Switching Loss vs. Gate Resistance**



**Figure 17. Switching Loss vs. Collector Current**



**Figure 18. Turn off Switching SOA Characteristics**



## Typical Performance Characteristics

Figure 19. Forward Characteristics

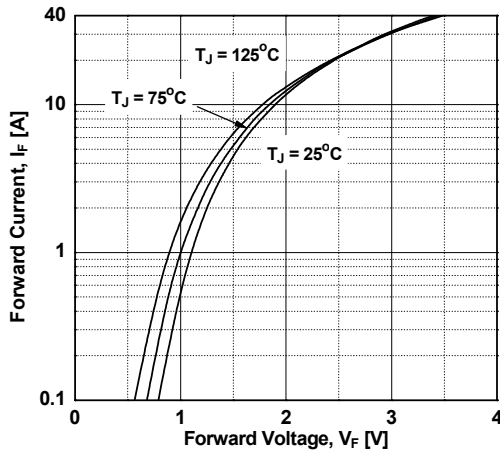


Figure 20. Reverse Current

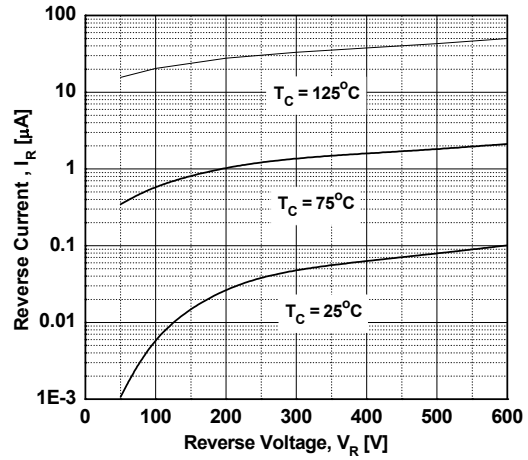


Figure 21. Stored Charge

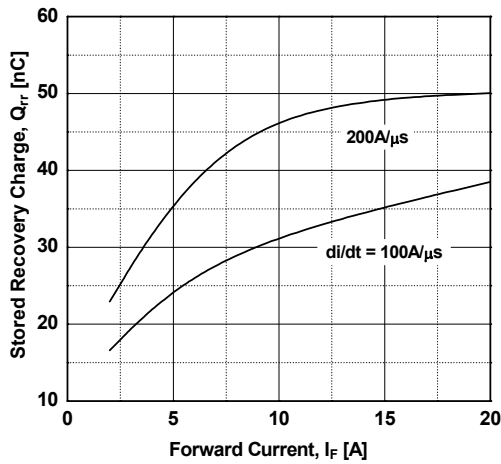


Figure 22. Reverse Recovery Time

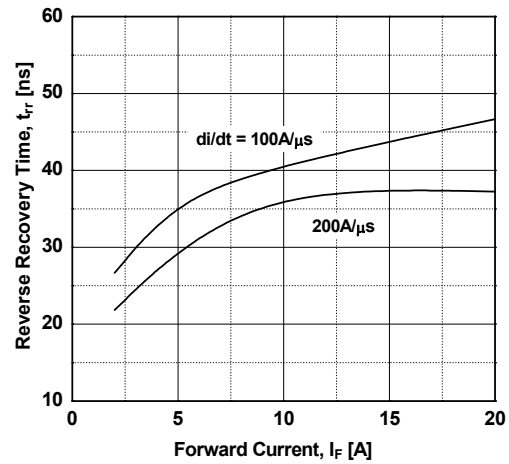
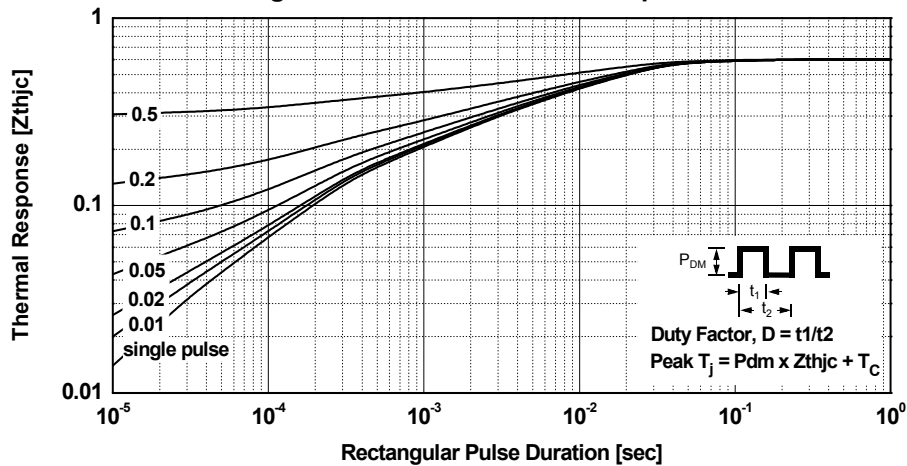
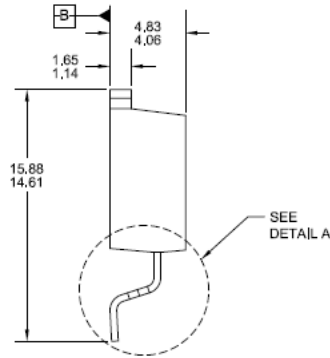
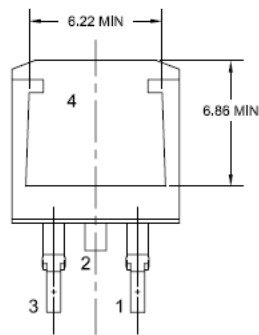
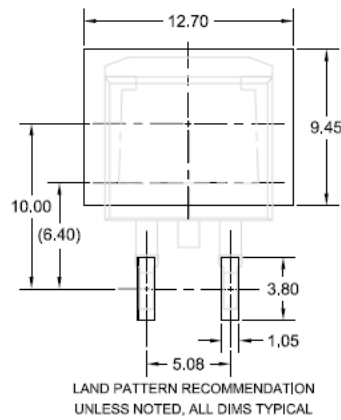
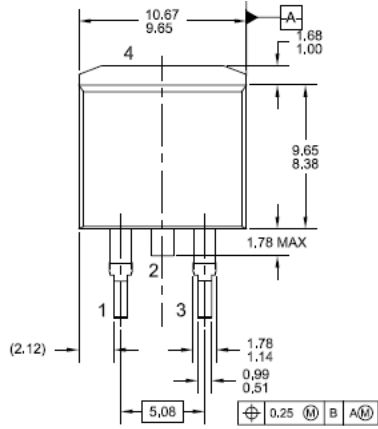


Figure 23. Transient Thermal Impedance of IGBT

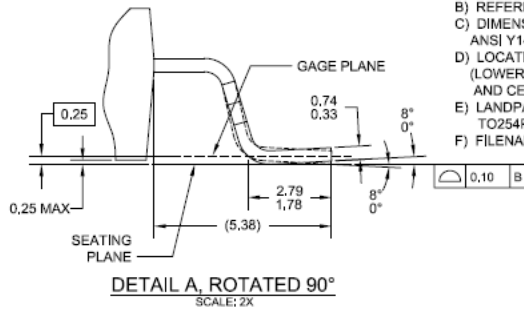


**Mechanical Dimensions**

**TO-263AB/D<sup>2</sup>-PAK**



- NOTES: UNLESS OTHERWISE SPECIFIED  
 A) ALL DIMENSIONS ARE IN MILLIMETERS.  
 B) REFERENCE JEDEC, TO-263, VARIATION AB.  
 C) DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1994.  
 D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).  
 E) LANDPATTERN RECOMMENDATION PER IPC TO254P1524X482-3N  
 F) FILENAME: TO263A02REV6







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| Build it Now™            | Global Power ResourceSM | PowerXS™                                     |  |
| CorePLUS™                | Green FPS™              | Programmable Active Droop™                   |  |
| CorePOWER™               | Green FPS™ e-Series™    | QFET®  |  |
| CROSSVOL™                | Gmax™                   | QS™  |  |
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| Current Transfer Logic™  | IntelliMAX™             | RapidConfigure™                              |  |
| DEUXPEED®                | ISOPLANAR™              | <p>Saving our world, 1mW/W/kW at a time™</p> |  |
| Dual Cool™               | MegaBuck™               | SignalWise™                                  |  |
| EcoSPARK®                | MICROCOUPLER™           | SmartMax™                                    |  |
| EfficientMax™            | MicroFET™               | SMART START™                                 |  |
| ESBC™                    | MicroPak™               | SPM®   |  |
| F®                       | MicroPak2™              | STEALTH™                                     |  |
| Fairchild®               | MillerDrive™            | SuperFET™                                    |  |
| Fairchild Semiconductor® | MotionMax™              | SuperSOT™-3                                  |  |
| FACT Quiet Series™       | Motion-SPM™             | SuperSOT™-6                                  |  |
| FACT®                    | OptiHiT™                | SuperSOT™-8                                  |  |
| FAST®                    | OPTOLOGIC®              | SupreMOS™                                    |  |
| FastvCore™               | OPTOPLANAR®             | SyncFET™                                     |  |
| FETBench™                |                         | Sync-Lock™                                   |  |
| FlashWriter® *           |                         |  |  |
| FPS™                     | PDP SPM™                |  |  |

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Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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